

LISTING OF THE CLAIMS

Please amend the claims as follows:

Claim 1 (Previously Presented): An elastic conductive resin composition, comprising an elastic resin and an acicular conductive filler, said filler having an aspect ratio of 5-200 and comprising a surface layer of gold, silver, nickel, or copper.

Claim 2 (Original): The elastic conductive resin composition according to claim 1, wherein the acicular conductive filler comprises a whisker as a core material.

Claim 3 (Original): The elastic conductive resin composition according to claim 2, wherein the acicular conductive filler comprises a high polymer whisker as a core material.

Claim 4 (Original): The elastic conductive resin composition according to claim 1, wherein the resin is a silicone resin having an ultraviolet-curing property and a humidity-curing property.

Claim 5 (Withdrawn): An electronic device, comprising:  
an electronic part comprising at least one first electrode;  
a substrate comprising at least one second electrode; and  
at least one bump formed on the at least one first electrode, said bump formed from the elastic conductive resin composition of claim 1,  
wherein the at least one first electrode and the at least one second electrode are electrically connected to each other by physical contact of the at least one bump with the at least one second electrode.

Claim 6 (Withdrawn): The electronic device according to claim 5, wherein the at least one bump has a shape that becomes gradually thin toward a tip portion of the at least one bump, and an aspect ratio of the at least one bump is in a range of about 0.1 to about 1.0.

Claim 7 (Withdrawn): The electronic device according to claim 5, wherein the resin is a silicone resin having an ultraviolet-curing property and a humidity-curing property.

Claim 8 (Withdrawn): An electronic device, comprising:  
an electronic part comprising at least one first electrode;  
a substrate comprising at least one second electrode; and  
at least one bump formed on the at least one second electrode, said bump formed from the elastic conductive resin composition of claim 1,  
wherein the at least one first electrode and the at least one second electrode are electrically connected to each other by physical contact of the at least one bump with the at least one first electrode.

Claim 9 (Withdrawn): The electronic device according to claim 8, wherein the at least one bump has a shape that becomes gradually thin toward a tip portion of the at least one bump, and an aspect ratio of the at least one bump is in a range of about 0.1 to about 1.0.

Claim 10 (Withdrawn): The electronic device according to claim 8, wherein the resin is a silicone resin having an ultraviolet-curing property and a humidity-curing property.

Claim 11 (Withdrawn): An electronic device, comprising:  
an electronic part comprising at least one first electrode;

a substrate comprising at least one second electrode;  
at least one bump formed on the at least one first electrode and formed from an elastic conductive composition comprising an elastic resin and a tetrapod-shaped zinc oxide filler comprising a surface layer of gold, silver, nickel, or copper,  
wherein the at least one first electrode and the at least one second electrode are electrically connected to each other by physical contact of the at least one bump with the at least one second electrode.

Claim 12 (Withdrawn): The electronic device according to claim 11, wherein the at least one bump has a shape that becomes gradually thin toward a tip portion of the at least one bump, and an aspect ratio of the at least one bump is in a range of about 0.1 to about 1.0.

Claim 13 (Withdrawn): The electronic device according to claim 11, wherein the resin is a silicone resin having an ultraviolet-curing property and a humidity-curing property.

Claim 14 (Withdrawn): An electronic device, comprising:  
an electronic part including at least one first electrode;  
a substrate including at least one second electrode;  
at least one bump formed on the at least one second electrode and formed from the elastic conductive resin composition of claim 1 wherein the filler is a tetrapod-shaped zinc oxide filler comprising a surface layer of gold, silver, nickel, or copper,  
wherein the at least one first electrode and the at least one second electrode are electrically connected to each other by physical contact of the at least one bump with the at least one first electrode.

Claim 15 (Withdrawn): The electronic device according to claim 14, wherein the at least one bump has a shape that becomes gradually thin toward a tip portion of the at least one bump, and an aspect ratio of the at least one bump is in a range of about 0.1 to about 1.0.

Claim 16 (Withdrawn): The electronic device according to claim 14, wherein the resin is a silicone resin having an ultraviolet-curing property and a humidity-curing property.

Claim 17 (Withdrawn): A connection part, comprising:  
an elastic conductive element formed from the elastic conductive resin composition of claim 1, and  
a metallic foil provided onto the elastic conductive element.

Claim 18 (Withdrawn): An electronic part comprising:  
at least one electrode; and  
at least one bump formed on the at least one electrode, said bump formed from the elastic conductive resin composition of claim 1.

Claim 19 (Withdrawn): A substrate comprising:  
at least one electrode; and  
at least one bump formed on the at least one electrode from the elastic conductive resin composition of claim 1.

Claim 20 (Withdrawn): A method of forming a bump on an electrode, comprising:  
screen-printing a conductive paste comprising a heat-curing silicone resin, a diluent, and an acicular conductive filler on said electrode;

heat-curing the conductive paste at a temperature lower than a complete curing temperature while evaporating the diluent; and

subsequently further heat-curing the conductive paste until a temperature of the conductive paste reaches the complete curing temperature.

Claim 21 (Withdrawn): A method of forming a connection part comprising an elastic conductive element formed from an elastic conductive resin composition comprising an elastic resin and an acicular conductive filler, and a metallic foil provided onto the elastic conductive element, comprising:

coating a metallic foil with the elastic conductive resin composition at a predetermined thickness;

curing the elastic conductive resin composition; and

cutting the cured elastic conductive resin composition and the metallic foil.

Claim 22 (Withdrawn): An electronic device, comprising:

an electronic part comprising at least one first electrode;

a substrate comprising at least one second electrode;

at least one bump formed on the at least one first electrode, and

at least one bump formed on the at least one second electrode, said bumps formed from the elastic conductive resin composition of claim 1,

wherein the at least one first electrode and the at least one second electrode are electrically connected to each other by physical contact a) of the at least one bump on the at least one first electrode with the at least one second electrode, and b) of the at least one bump on the at least one second electrode with the at least one first electrode.

Claim 23 (Withdrawn): An electronic device, comprising:

- an electronic part comprising at least one first electrode;
- a substrate comprising at least one second electrode;
- at least one bump formed on the at least one first electrode and formed from an elastic conductive composition comprising an elastic resin and a tetrapod-shaped zinc oxide filler comprising a surface layer of gold, silver, nickel, or copper,
- at least one bump formed on the at least one second electrode and formed from an elastic conductive composition comprising an elastic resin and a tetrapod-shaped zinc oxide filler comprising a surface layer of gold, silver, nickel, or copper,

wherein the at least one first electrode and the at least one second electrode are electrically connected to each other by physical contact of the at least one bump thereon with the other electrode.

Claim 24 (Previously Presented): The elastic conductive resin composition according to claim 1, wherein the aspect ratio of the acicular conductive filler is 20-40.

Claim 25 (Previously Presented): The elastic conductive resin according to claim 1, wherein the aspect ratio of the acicular conductive filler is 20-50.